



## Features

- Four, six and eight channels of EMI filtering with integrated ESD protection
- Pi-style EMI filters in a capacitor-resistor-capacitor (C-R-C) network
- $\pm 15\text{kV}$  ESD protection on each channel (IEC 61000-4-2 Level 4, contact discharge)
- $\pm 30\text{kV}$  ESD protection on each channel (HBM)
- Greater than 20dB attenuation (typical) at 1 GHz
- TDFN package with 0.40mm lead pitch:
  - 4-ch. = 8-lead TDFN
  - 6-ch. = 12-lead TDFN
  - 8-ch. = 16-lead TDFN
- Tiny TDFN package size:
  - 8-lead: 1.7mm x 1.35mm
  - 12-lead: 2.5mm x 1.35mm
  - 16-lead: 3.3mm x 1.35mm
- Increased robustness against vertical impacts during manufacturing process
- Lead-free version available

## Applications

- LCD and Camera data lines in mobile handsets
- I/O port protection for mobile handsets, notebook computers, PDAs etc.
- EMI filtering for data ports in cell phones, PDAs or notebook computers.
- Wireless handsets
- Handheld PCs/PDAs
- LCD and camera modules

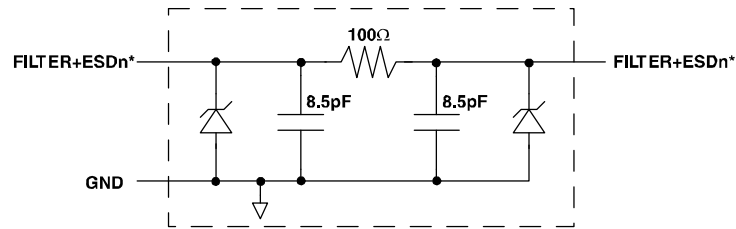
## Product Description

The CM1430 is a family of pi-style EMI filter arrays with ESD protection, which integrates four, six and eight filters (C-R-C) in small form factor TDFN 0.40mm pitch packages. The CM1430 has component values of 8.5pF-100 $\Omega$ -8.5pF per channel. The CM1430 has a cut-off frequency of 200MHz and can be used in applications with data rates up to 80Mbps. The parts include ESD diodes on every pin, which provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD protection diodes safely dissipate ESD strikes of  $\pm 15\text{kV}$ , well beyond the maximum requirement of the IEC61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than  $\pm 30\text{kV}$ .

These devices are particularly well-suited for portable electronics (e.g. wireless handsets, PDAs, notebook computers) because of their small package and easy-to-use pin assignments. In particular, the CM1430 is ideal for EMI filtering and protecting data and control lines for the I/O data ports, LCD display and camera interface in mobile handsets.

The CM1430 is housed in space-saving, low-profile 8-, 12- and 16-lead TDFN packages with a 0.4mm pitch and is available with lead-free finishing. This new small TDFN package provides up to 42% board space savings vs. the 0.50mm pitch TDFN packages.

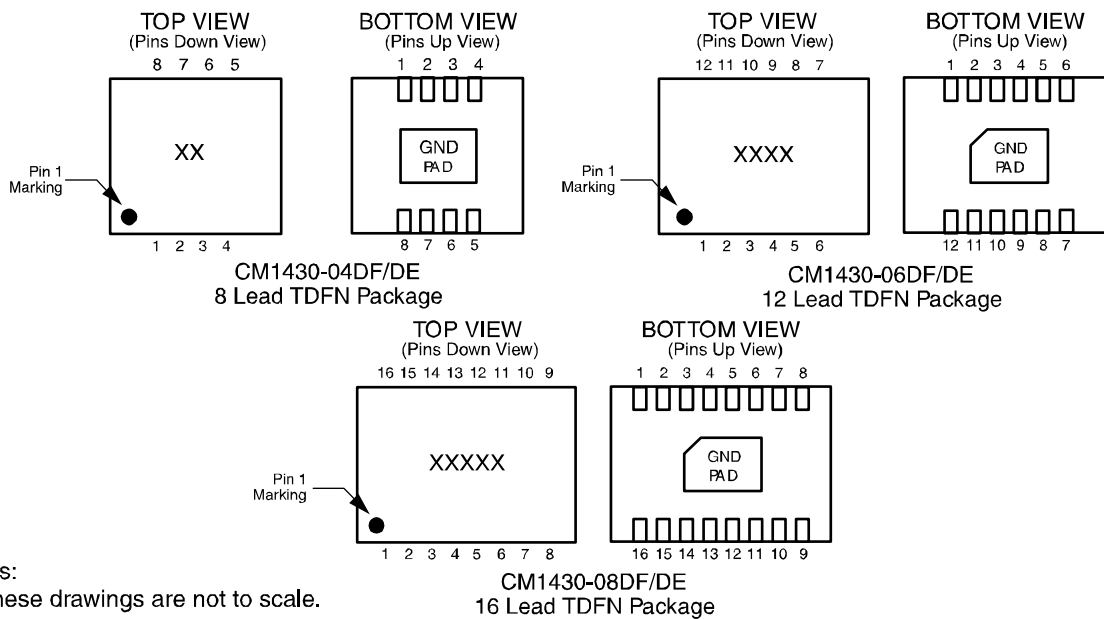
**Electrical Schematic**



**1 of 4, 6 or 8 EMI/RFI Filter Channels with Integrated ESD Protection**

\* See Package/Pinout Diagram for expanded pin information.

**PACKAGE / PINOUT DIAGRAMS**



**PIN DESCRIPTIONS**

DEVICE PIN(s)			NAME	DESCRIPTION	DEVICE PIN(s)			NAME	DESCRIPTION
-04	-06	-08			-04	-06	-08		
1	1	1	FILTER1	Filter + ESD Channel 1	8	12	16	FILTER1	Filter + ESD Channel 1
2	2	2	FILTER2	Filter + ESD Channel 2	7	11	15	FILTER2	Filter + ESD Channel 2
3	3	3	FILTER3	Filter + ESD Channel 3	6	10	14	FILTER3	Filter + ESD Channel 3
4	4	4	FILTER4	Filter + ESD Channel 4	5	9	13	FILTER4	Filter + ESD Channel 4
	5	5	FILTER5	Filter + ESD Channel 5		8	12	FILTER5	Filter + ESD Channel 5
	6	6	FILTER6	Filter + ESD Channel 6		7	11	FILTER6	Filter + ESD Channel 6
		7	FILTER7	Filter + ESD Channel 7			10	FILTER7	Filter + ESD Channel 7
		8	FILTER8	Filter + ESD Channel 8			9	FILTER8	Filter + ESD Channel 8
GND PAD			GND	Device Ground					

**Ordering Information**

**PART NUMBERING INFORMATION**

Pins	Package	Standard Finish		Lead-free Finish	
		Ordering Part Number <sup>1</sup>	Part Marking	Ordering Part Number <sup>1</sup>	Part Marking
8	TDFN-8	CM1430-04DF	VF	CM1430-04DE	VE
12	TDFN-12	CM1430-06DF	N30F	CM1430-06DE	N30E
16	TDFN-16	CM1430-08DF	N308F	CM1430-08DE	N308E

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

**Specifications**

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	RATING	UNITS
Storage Temperature Range	-65 to +150	°C
DC Power per Resistor	100	mW
DC Package Power Rating	500	mW

### STANDARD OPERATING CONDITIONS

PARAMETER	RATING	UNITS
Operating Temperature Range	-40 to +85	°C

### ELECTRICAL OPERATING CHARACTERISTICS (SEE NOTE1)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
R	Resistance		80	100	120	$\Omega$
C <sub>TOTAL</sub>	Total Channel Capacitance	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	14	17	22	pF
C	Capacitance C1	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	7	8.5	11	pF
V <sub>DIODE</sub>	Standoff Voltage	I <sub>DIODE</sub> =10 $\mu$ A		6.0		V
I <sub>LEAK</sub>	Diode Leakage Current (reverse bias)	V <sub>DIODE</sub> =+3.3V		0.1	1.0	$\mu$ A
V <sub>SIG</sub>	Signal Clamp Voltage Positive Clamp Negative Clamp	I <sub>LOAD</sub> = 10mA I <sub>LOAD</sub> = -10mA	5.6 -1.5	6.8 -0.8	9.0 -0.4	V V
V <sub>ESD</sub>	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	Note 2	30 15			kV kV
R <sub>DYN</sub>	Dynamic Resistance Positive Negative			2.3 0.9		$\Omega$ $\Omega$
f <sub>c</sub>	Cut-off Frequency Z <sub>SOURCE</sub> =50 $\Omega$ , Z <sub>LOAD</sub> =50 $\Omega$	Channel R = 100 $\Omega$ , Channel C = 8.5pF		200		MHz

Note 1: T<sub>A</sub>=25°C unless otherwise specified.

Note 2: ESD applied to input and output pins with respect to GND, one at a time.

## Performance Information

Typical Filter Performance ( $T_A=25^\circ\text{C}$ , DC Bias=0V, 50 Ohm Environment)

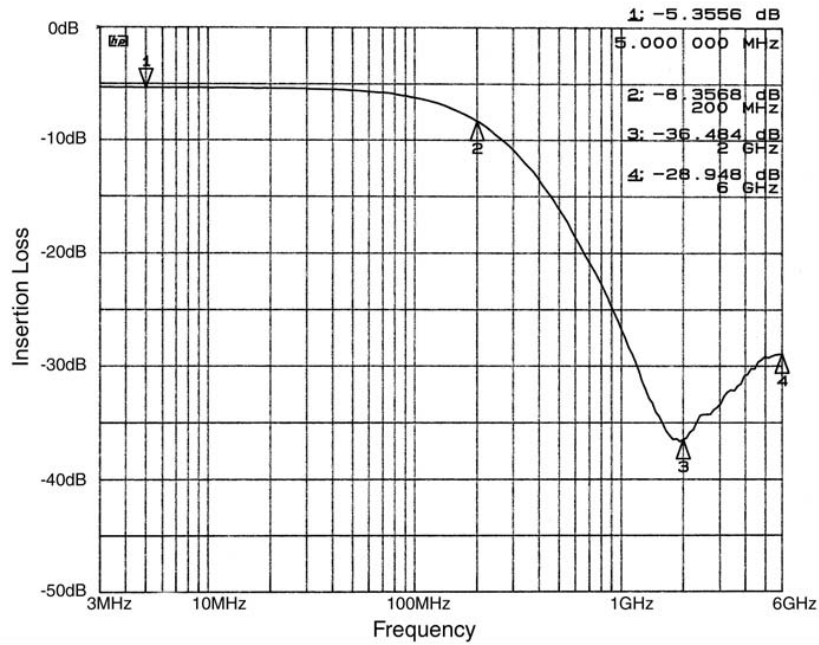


Figure 1. Insertion Loss vs. Frequency (FILTER1 Input to GND)

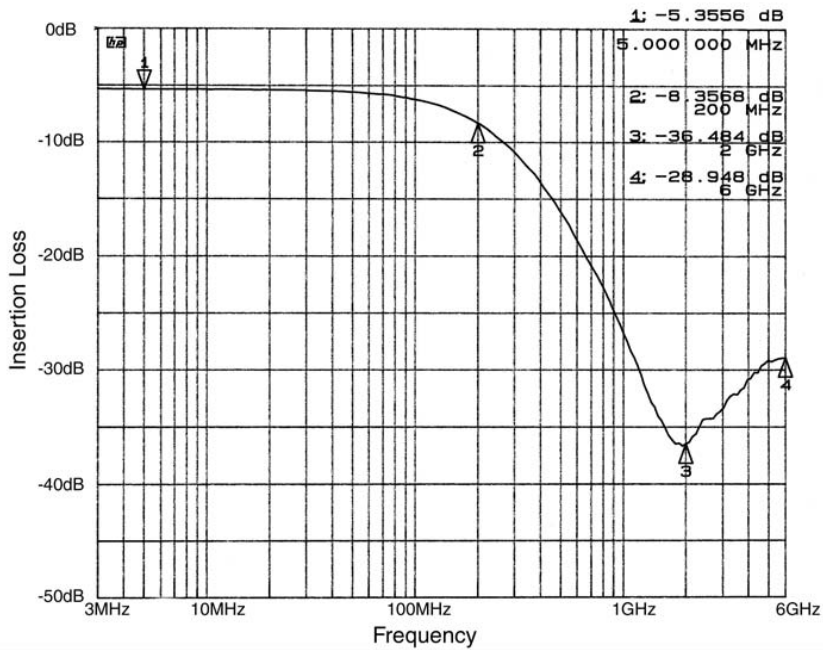


Figure 2. Insertion Loss vs. Frequency (FILTER2 Input to GND)

## Performance Information (cont'd)

Typical Filter Performance ( $T_A=25^\circ\text{C}$ , DC Bias=0V, 50 Ohm Environment)

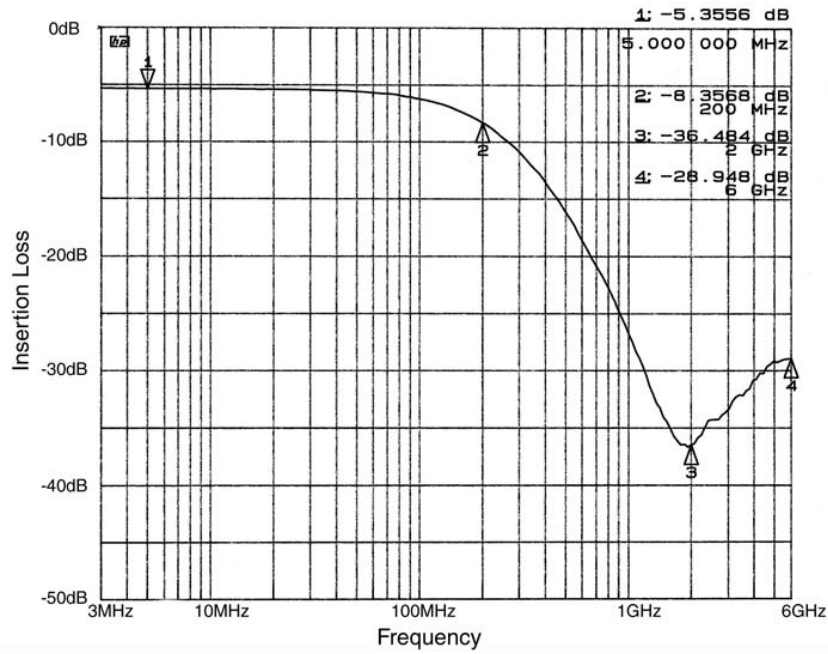


Figure 3. Insertion Loss vs. Frequency (FILTER3 Input to GND)

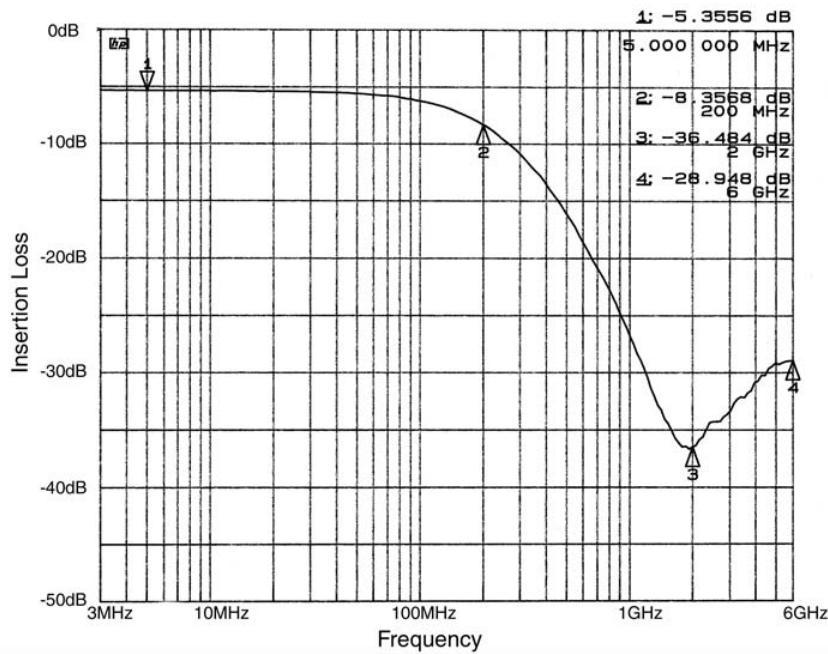
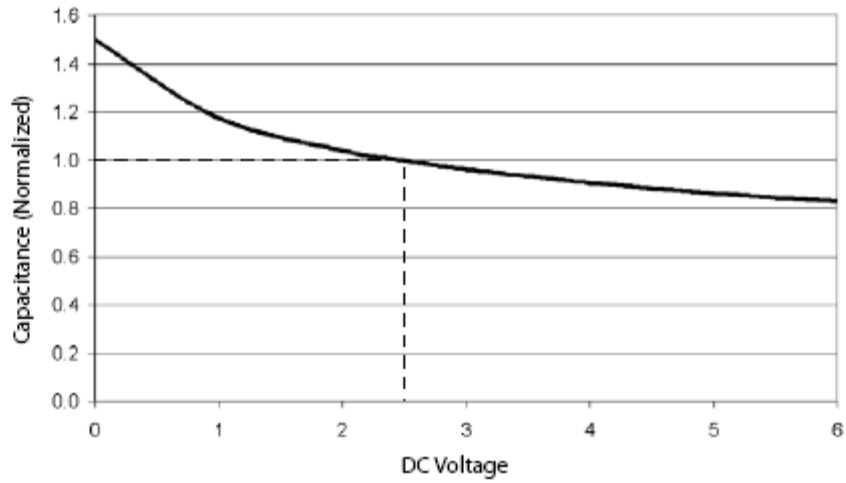


Figure 4. Insertion Loss vs. Frequency (FILTER4 Input to GND)

## Performance Information (cont'd)

### Typical Diode Capacitance vs. Input Voltage



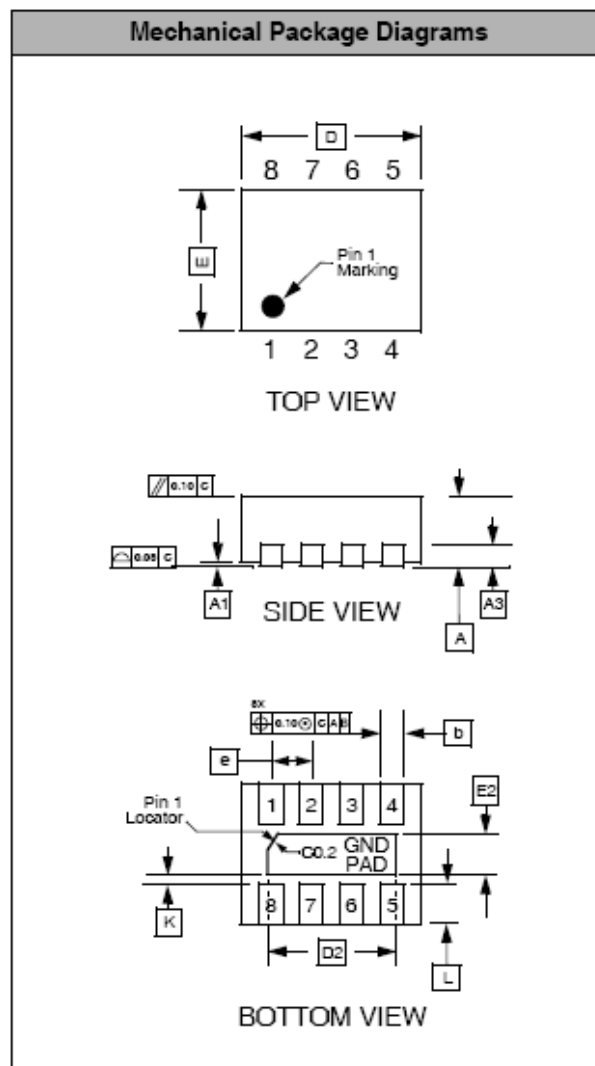
**Figure 5. Filter Capacitance vs. Input Voltage  
(normalized to capacitance at 2.5VDC and 25°C)**

## Mechanical Details

### CM1430-04DF/DE Mechanical Specifications

Dimensions for the CM1430-04DF/DE supplied in a 8-lead, 0.4mm pitch TDFN package are presented below. For complete information on the TDFN-8, see the California Micro Devices TDFN Package Information document.

PACKAGE DIMENSIONS						
Package	TDFN					
JEDEC No.	MO-229C					
Leads	8					
Dim.	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.20 REF			0.008 REF		
b	0.15	0.20	0.25	0.006	0.008	0.010
D	1.60	1.70	1.80	0.063	0.067	0.071
D2	1.10	1.20	1.30	0.043	0.047	0.051
E	1.25	1.35	1.45	0.049	0.053	0.057
E2	0.30	0.40	0.50	0.012	0.016	0.020
e	0.40 BSC			0.016 BSC		
K	0.20			0.008		
L	0.15	0.25	0.35	0.006	0.010	0.014
# per tape and reel	3000 pieces					
Controlling dimension: millimeters						



Dimensions for 8-Lead, 0.4mm pitch TDFN package

This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

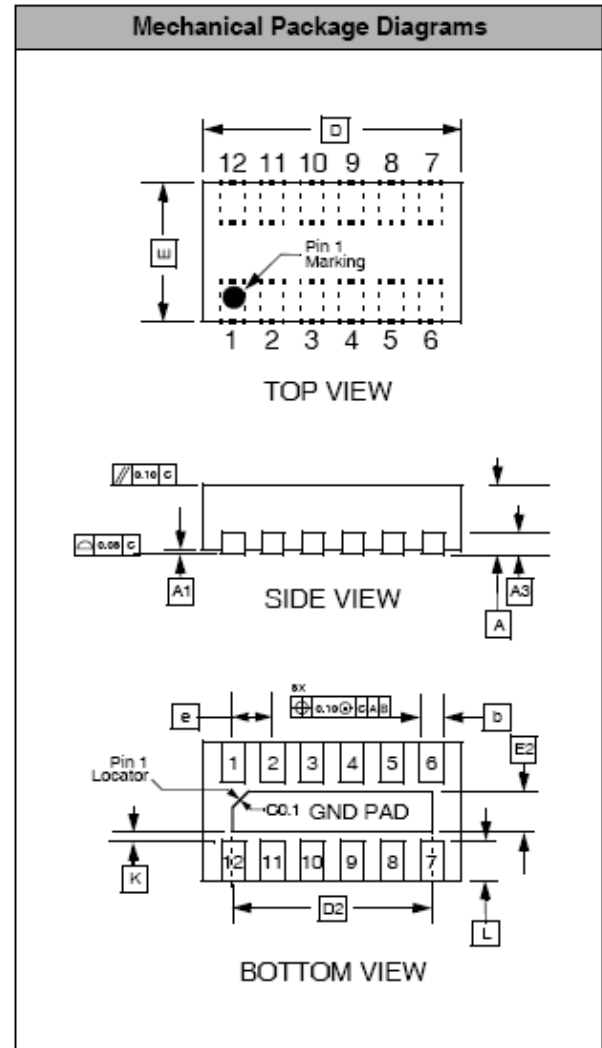


## Mechanical Details (cont'd)

### CM1430-06DF/DE Mechanical Specifications

Dimensions for the CM1430-06DF/DE supplied in a 12-lead, 0.4mm pitch TDFN package are presented below.

PACKAGE DIMENSIONS						
Package	TDFN					
JEDEC No.	MO-229C					
Leads	12					
Dim.	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.20 REF			0.008 REF		
b	0.15	0.20	0.25	0.006	0.008	0.010
D	2.40	2.50	2.60	0.094	0.098	0.102
D2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.25	1.35	1.45	0.049	0.053	0.057
E2	0.30	0.40	0.50	0.012	0.016	0.020
e	0.40 BSC			0.016 BSC		
K	0.20			0.008		
L	0.15	0.25	0.35	0.006	0.010	0.014
# per tape and reel	3000 pieces					
Controlling dimension: millimeters						



Dimensions for 12-Lead, 0.4mm pitch TDFN package

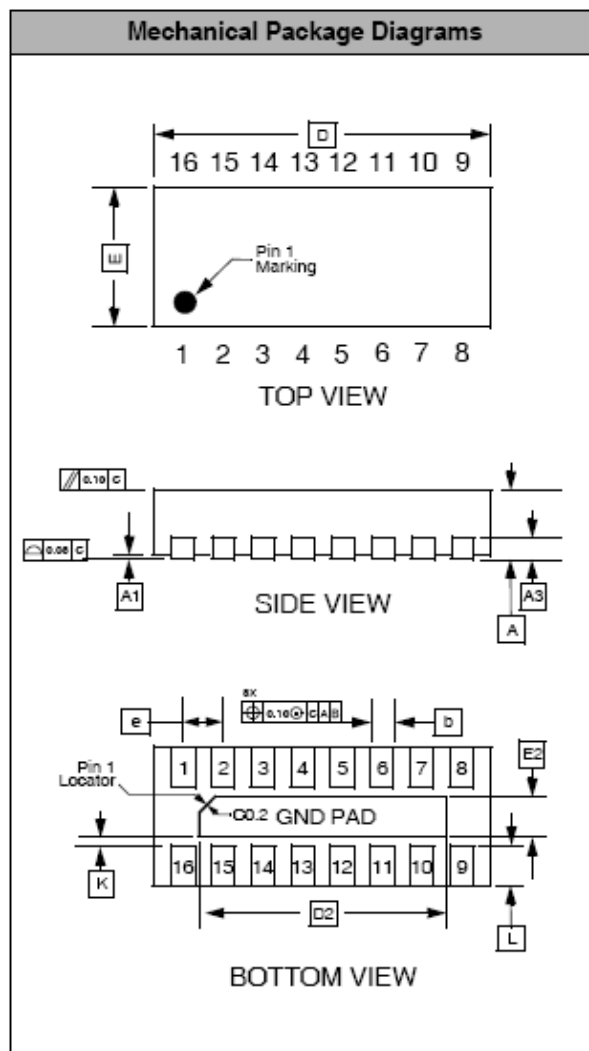
This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

## Mechanical Details (cont'd)

### CM1430-08DF/DE Mechanical Specifications


Dimensions for the CM1430-08DF/DE supplied in a 16-lead, 0.4mm pitch TDFN package are presented below. For complete information on the TDFN-16, see the California Micro Devices TDFN Package Information document.

PACKAGE DIMENSIONS						
Package	TDFN					
JEDEC No.	MO-229C					
Leads	16					
Dim.	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.200 REF			0.008 REF		
b	0.15	0.20	0.25	0.006	0.008	0.010
D	3.20	3.30	3.40	0.126	0.130	0.134
D2	2.70	2.80	2.90	0.106	0.110	0.114
E	1.25	1.35	1.45	0.049	0.053	0.057
E2	0.30	0.40	0.50	0.012	0.016	0.020
e	0.40 BSC			0.016 BSC		
K	0.20			0.008		
L	0.15	0.25	0.35	0.006	0.010	0.014
# per tape and reel	3000 pieces					
Controlling dimension: millimeters						



Dimensions for 16-Lead, 0.4mm pitch TDFN package

This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

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